

TECHNICAL CHARACTERISTICS

1. General Characteristics

Dimension: 17.95L x 15.30W x 1.80H mm
 Weight: Approx. 0.72 g
 Contact principle: Friction technology
 Operating position: Shaft up / Down / Horizontal
 Mounting System: SMT Type (without post)
 Function: Hinge Type
 Durability: 5,000 cycles min.

2. Mechanical Characteristics

Insulation material: Thermoplastic, UL 94V-0
 RoHS Directive 2011/65/EU Compliant

3. Electrical Characteristics

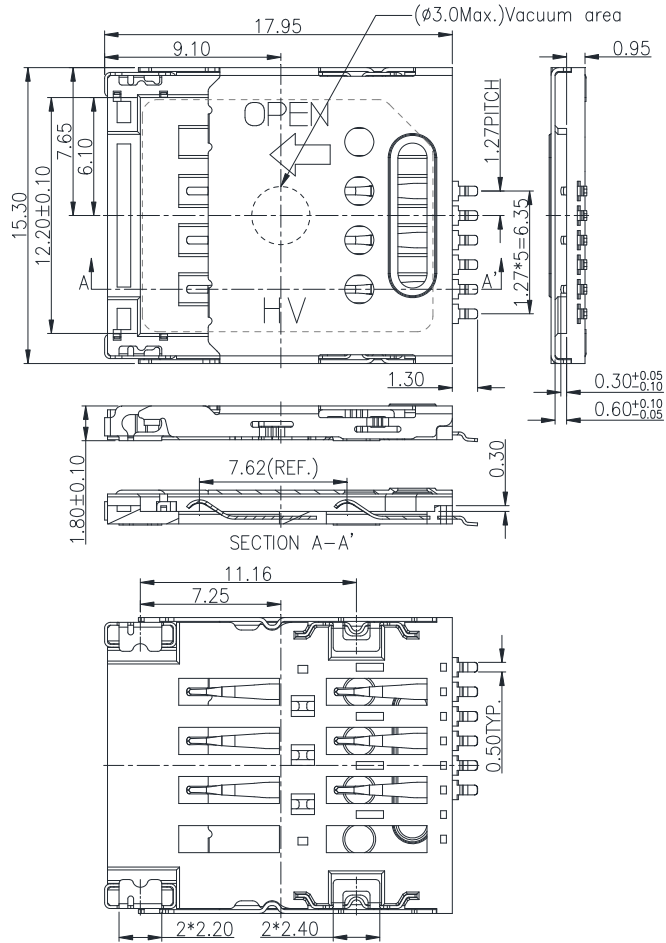
Number of contacts: 6, 8 pins (optional)
 Contact resistance: 50 mΩ typical, 100 mΩ max.
 Insulation resistance: >1000 MΩ / 500 VDC

4. Solderability

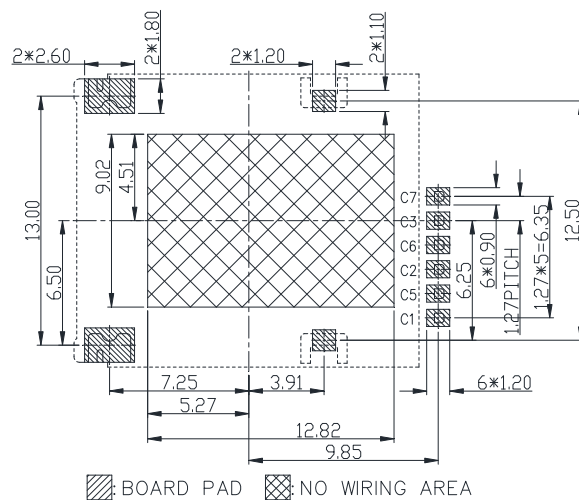
Wave: Not applicable
 IR reflow: 260°C, 10 sec. Max.
 Manual soldering: 360°C, 3 sec. Max.

5. Environmental Characteristics

Operating temperature: - 40°C ~ + 85°C
 Operating humidity: 10 % ~ 95 % RH
 Storage temperature: - 40°C ~ + 85°C
 Storage humidity: 10 % ~ 95 % RH



Unit: mm; Tolerances: ±0.15 mm
 Mechanical outline dimension



Unit: mm; Tolerances: ±0.05 mm
 Reference dimension for PCB layout

H&V Micro SIM Card Connector

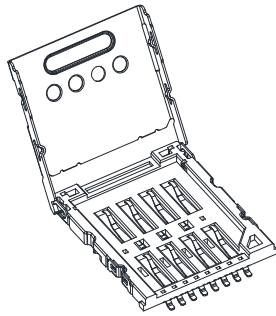
Model No.: ICC-M02 6Pin

Revision: 1.0

Date: MAY 01, 2014

Note:

1. Coplanarity of solder pins 0.10mm max.
2. Recommended thickness of solder paste > 0.15mm.



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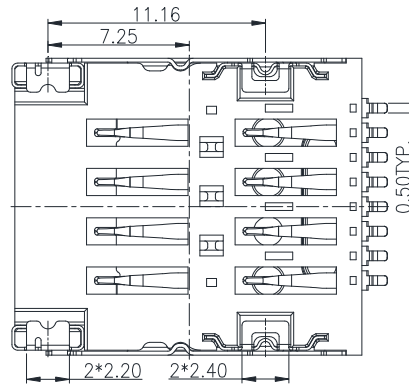
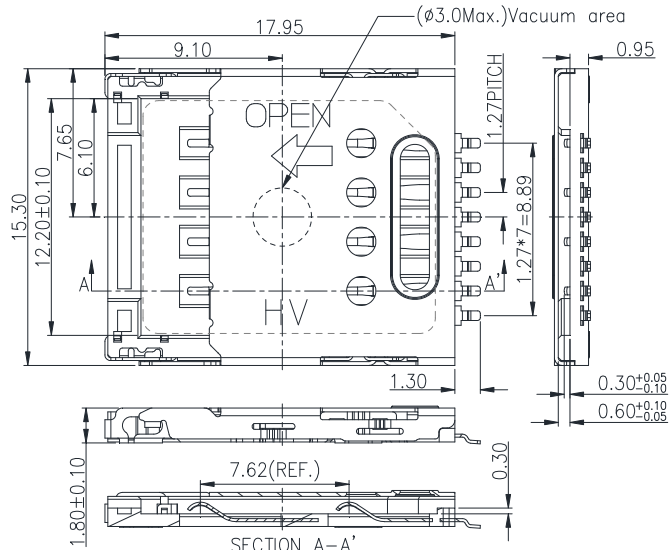
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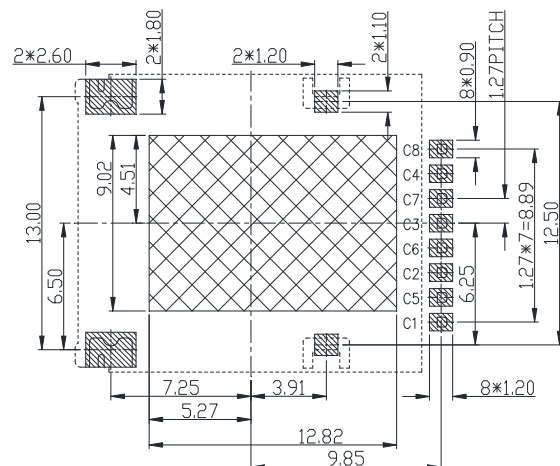
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 Operating humidity: 10 % ~ 95 % RH
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Unit: mm; Tolerances: ±0.15 mm
Mechanical outline dimension



▨ BOARD PAD ▩ NO WIRING AREA

Unit: mm; Tolerances: ±0.05 mm
Reference dimension for PCB layout

H&V Micro SIM Card Connector

Model No.: ICC-M02 8Pin

Revision: 1.0

Date: MAY 01, 2014

Note:

- Coplanarity of solder pins 0.10mm max.
- Recommended thickness of solder paste > 0.15mm.